L Number	Hits	Search Text	DB	Time stamp
1	2582466	die chip dice semiconductor miicroelectronic ic (integrated adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 05:09
2	805082	(((printed wiring circuit) adj5 board) carrier substrate board pcb support) same (die chip dice semiconductor miicroelectronic ic (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 05:11
3	162024	((((printed wiring circuit) adj5 board) carrier substrate board pcb support) same (die chip dice semiconductor miicroelectronic ic (integrated adj circuit))) same (stack stacked stacking mounted mounting mount stackable mount mounted mounting mountable)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 05:13
4	36617	(((((printed wiring circuit) adj5 board) carrier substrate board pcb support) same (die chip dice semiconductor miicroelectronic ic (integrated adj circuit))) same (stack stacked stacking mounted mounting mount stackable mount mounted mounting mountable)) AND (ball bump flipchip (flip adj3 (chip die)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 05:14
5	17360	((((((printed wiring circuit) adj5 board) carrier substrate board pcb support) same (die chip dice semiconductor miicroelectronic ic (integrated adj circuit))) same (stack stacked stacking mounted mounting mount stackable mount mounted mounting mountable)) AND (ball bump flipchip (flip adj3 (chip die)))) and (lead leadframe (lead adj frame) loc)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 05:15
6	12911	(package packaging packaged) and ((((((printed wiring circuit) adj5 board) carrier substrate board pcb support) same (die chip dice semiconductor miicroelectronic ic (integrated adj circuit))) same (stack stacked stacking mounted mounting mount stackable mount mounted mounting mountable)) AND (ball bump flipchip (flip adj3 (chip die)))) and (lead leadframe (lead adj frame) loc))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 05:20
7	2504	257/777	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 05:20
8	3726	257/723	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 05:20
9	4071	257/778	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 05:20
10	2736	257/686	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 05:21

11	5342	257/666	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 05:21
12	1029	257/679	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 05:21
13	1182	257/685	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 05:21
14	805	257/673	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 05:21
15	2069	257/734	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 05:22
16	3317	257/737	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 05:22
17	2758	257/738	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 05:22
18	17486	257/777 257/723 257/778 257/686 257/666 257/679 257/685 257/673 257/734 257/737 257/738	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 05:22
19	4276	((package packaging packaged) and ((((((printed wiring circuit) adj5 board) carrier substrate board pcb support) same (die chip dice semiconductor miicroelectronic ic (integrated adj circuit))) same (stack stacked stacking mounted mounting mount stackable mount mounted mounting mountable)) AND (ball bump flipchip (flip adj3 (chip die)))) and (lead leadframe (lead adj frame) loc))) and (257/777 257/723 257/778 257/686 257/666 257/679 257/685 257/673 257/734 257/737 257/738)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 05:24
20	3361	(((package packaging packaged) and ((((((printed wiring circuit) adj5 board) carrier substrate board pcb support) same (die chip dice semiconductor miicroelectronic ic (integrated adj circuit))) same (stack stacked stacking mounted mounting mount stackable mount mounted mounting mountable)) AND (ball bump flipchip (flip adj3 (chip die)))) and (lead leadframe (lead adj frame) loc))) and (257/777 257/723 257/778 257/686 257/666 257/679 257/685 257/673 257/734 257/737 257/738)) and (different difference)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 05:25

21	2199	((((package packaging packaged) and ((((((printed wiring circuit) adj5 board) carrier substrate board pcb support) same (die chip dice semiconductor miicroelectronic ic (integrated adj circuit))) same (stack stacked stacking mounted mounting mount stackable mount mounted mounting mountable)) AND (ball bump flipchip (flip adj3 (chip die)))) and (lead leadframe (lead adj frame) loc))) and (257/777 257/723 257/778 257/686 257/666 257/679 257/685 257/673 257/734 257/737 257/738)) and (different difference)) and (encapsulating encapsulated encapsulation encapsulant mold molded encased encase encasing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 05:27
22	1946	solder and (((((package packaging packaged) and ((((((printed wiring circuit) adj5 board) carrier substrate board pcb support) same (die chip dice semiconductor miicroelectronic ic (integrated adj circuit))) same (stack stacked stacking mounted mounting mount stackable mount mounted mounting mountable)) AND (ball bump flipchip (flip adj3 (chip die)))) and (lead leadframe (lead adj frame) loc))) and (257/777 257/723 257/778 257/686 257/666 257/679 257/685 257/673 257/734 257/737 257/738)) and (different difference)) and (encapsulating encapsulated encapsulation encapsulant mold molded encased encase encasing))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/31 05:28
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26	1		USPAT	2004/08/31 06:06
27	1		USPAT	2004/08/31 06:07
28	1		USPAT	2004/08/31 06:07
29	1		USPAT	2004/08/31 06:07
30	1		USPAT	2004/08/31 06:07
31	1		USPAT	2004/08/31 06:07
32	1		USPAT	2004/08/31 06:07
33	1		USPAT	2004/08/31 06:07
34	1		USPAT	2004/08/31 06:07
35	1		USPAT	2004/08/31 06:08
36	1		USPAT	2004/08/31 06:08
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